MP-1 Crystals

THIS PRODUCT IS NOT RECOMMENDED FOR NEW DESIGNS.





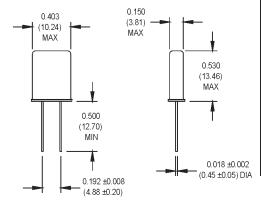


Order by:

MP-1-R (HC-49/U) 00.0000 MHz (Frequency)

Custom P/N:

M1002Sxxx - Contact factory for datasheet



All dimensions in inches (mm).

Equivalent Series Resistance (ESR), Max. Fundamental (AT-cut)	MP-1
1.8432 to 1.999 MHz	700 Ω
2.000 to 2.399 MHz	600 Ω
2.400 to 3.299 MHz	400 Ω
3.300 to 3.569 MHz	140 Ω
3.570 to 3.999 MHz	100 Ω
4.000 to 5.999 MHz	75 Ω
6.000 to 7.999 MHz	50 Ω
8.000 to 10.999 MHz	40 Ω
11.000 to 14.999 MHz	30 Ω
15.000 to 19.999 MHz	25 Ω
20.000 to 34.000 MHz	25 Ω
Third Overtones (AT-cut)	Note 2
20.000 to 49.999 MHz	40 Ω
50.000 to 75.000 MHz	50 Ω
Fifth Overtones (AT-cut)	Note 3
50.000 to 125.000 MHz	90 Ω
Seventh Overtones (AT-cut)	Note 4
125.000 to 200.000 MHz	150 Ω

0.435	
(11.05)	0.183
MAX	(4.65
	₩ MAX
	'
\odot	<u>, </u>
	A
	I

	PARAMETER	Symbol	Min.	Тур.	Max.	Units	Condition/Notes
ons	Frequency Range	F	1.8432		200	MHz	
	Frequency Tolerance	F/F	-30		+30	ppm	
ificati	Frequency Stability	ΔF/F	-50		+50	ppm	
ific	Operating Temperature	T _A	-10		+70	$_{\mathbb{C}}$	
peci	Storage Temperature	Ts	-55		+125	$_{\mathbb{C}}$	
S	Aging Per Year			±5	±5		
cal	Load Capacitance	C_L		18		pF	See Note 1
lectri	Shunt Capacitance	Co			7	pF	
<u> e</u>	ESR		See ESR Table				
Ш	Drive Level	D_L	50	100	1000	μW	
	Insulation Resistance	I _R	500			ΜΩ	
	Mechanical Shock	MIL-STD-202, Method 213, C (100 g's)					
ıtal	Vibration	MIL-STD-202, Method 201 & 204 (10 g's from 10-2000 Hz)					
vironmenta	Thermal Cycle	MIL-STD-883, Method 1010, B (-55°C to 125°C, 15 min dwell, 10 cycles)					
onr	Hermeticity	MIL-STD-202, Method 112 (1 x 10 ⁻⁸ atmcc/sec. min.)					
vir	Solderability	Per EIAJ-STD-002					
En	Max Wave Soldering Conditions	+260 ℃ for 10 secs. Max.					

Note 1: Series resonant designated "SR" prefix (i.e., SRMP-1-R) Note 2: Order by P/N 302-000-R-Frequency Note 3: Order by P/N 309-000-R-Frequency. This is a series resonant part.

Note 4: Order by P/N 320-000-R-Frequency. This is a series resonant part.

MtronPTI reserves the right to make changes to the product(s) and service(s) described herein without notice. No liability is assumed as a result of their use or application.